

# CHIP SENTRY CARRIER OPENING PROCEDURE

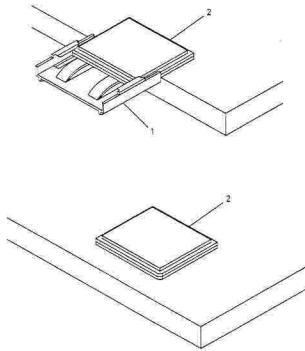
CAUTION



## ELECTROSTATIC SENSITIVE

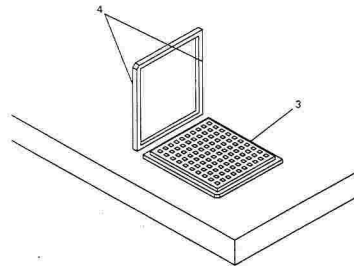
The die is an electrostatic sensitive device. Special handling methods and equipment must be used to prevent damage.

1. Ensure inspection area is ESD compliant. A clean room environment is desirable to minimize foreign material contamination.
2. Carefully remove chip sentry carriers from shipping containers.
3. Align non-restricted side of chip sentry carrier along table edge so that clip (1) is just under table edge and waffle pack (2) edge can be moved freely onto table surface.
4. Holding bottom of clip (1) with index fingers, press top of waffle pack (2) with thumbs and slide waffle pack onto table surface.

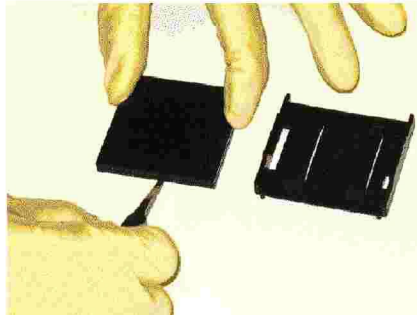


Do not attempt to open waffle pack by holding it in one hand and opening with other hand. Waffle pack bottom must remain flat on table to prevent damage to die.

5. Ensuring waffle pack bottom (3) remains on table, gently grasp two edges of waffle pack top (4) and slowly lift top as though hinged.



6. If resistance occurs when attempting to open the lid, place a thin flat-surfaced metal object (such as tweezers or blade) into the crevice between the top and bottom of the waffle pack. Using minimum pressure, separate the waffle pack while maintaining the position on the desk surface. Do not attempt to complete this step while a waffle pack is being held in hands. When the top is loosened, continue removing the lid using step 5 above.



7. Inspect chip as required.